

## PATENT ABSTRACTS OF JAPAN

(11)Publication number : 01-240683

(43)Date of publication of application : 26.09.1989

(51)Int.Cl.

G23F 1/18

(21)Application number : 63-066709

(71)Applicant : SANSHIN KAGAKU KOGYO KK

(22)Date of filing : 19.03.1988

(72)Inventor : YAMAMOTO YOSHINARI  
AKASHI SUMIO

## (54) COMPOSITION OF ETCHING SOLUTION FOR COPPER AND ETCHING METHOD

## (57)Abstract:

PURPOSE: To prepare the compsn. of an etching soln. in which the lowering of etching speed by chloric ions is prevented by adding effective amounts of benzotriazole to an etching soln. contg. specific ratios of sulfuric acid and hydrogen peroxide.

CONSTITUTION: Benzotriazole and/or tolyltriazole, 100-5000ppm, is incorporated into an etching soln. contg. 5-25vol.% sulfuric acid and 3-20vol.% hydrogen peroxide to prepare the compsn. of an etching soln. for copper. By this method, the compsn. of the etching soln. for copper in which the deterioration caused by chloric ions is prevented without drastically lowering the etching speed even if hydrogen ions contained in city water are mingled can be obtd.

## LEGAL STATUS

[Date of request for examination]

[Date of sending the examiner's decision of rejection]

[Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]

[Date of final disposal for application]

[Patent number]

[Date of registration]

[Number of appeal against examiner's decision of rejection]

[Date of requesting appeal against examiner's decision of rejection]

[Date of extinction of right]

Copyright (C); 1998,2003 Japan Patent Office

**THIS PAGE BLANK (USPTO)**